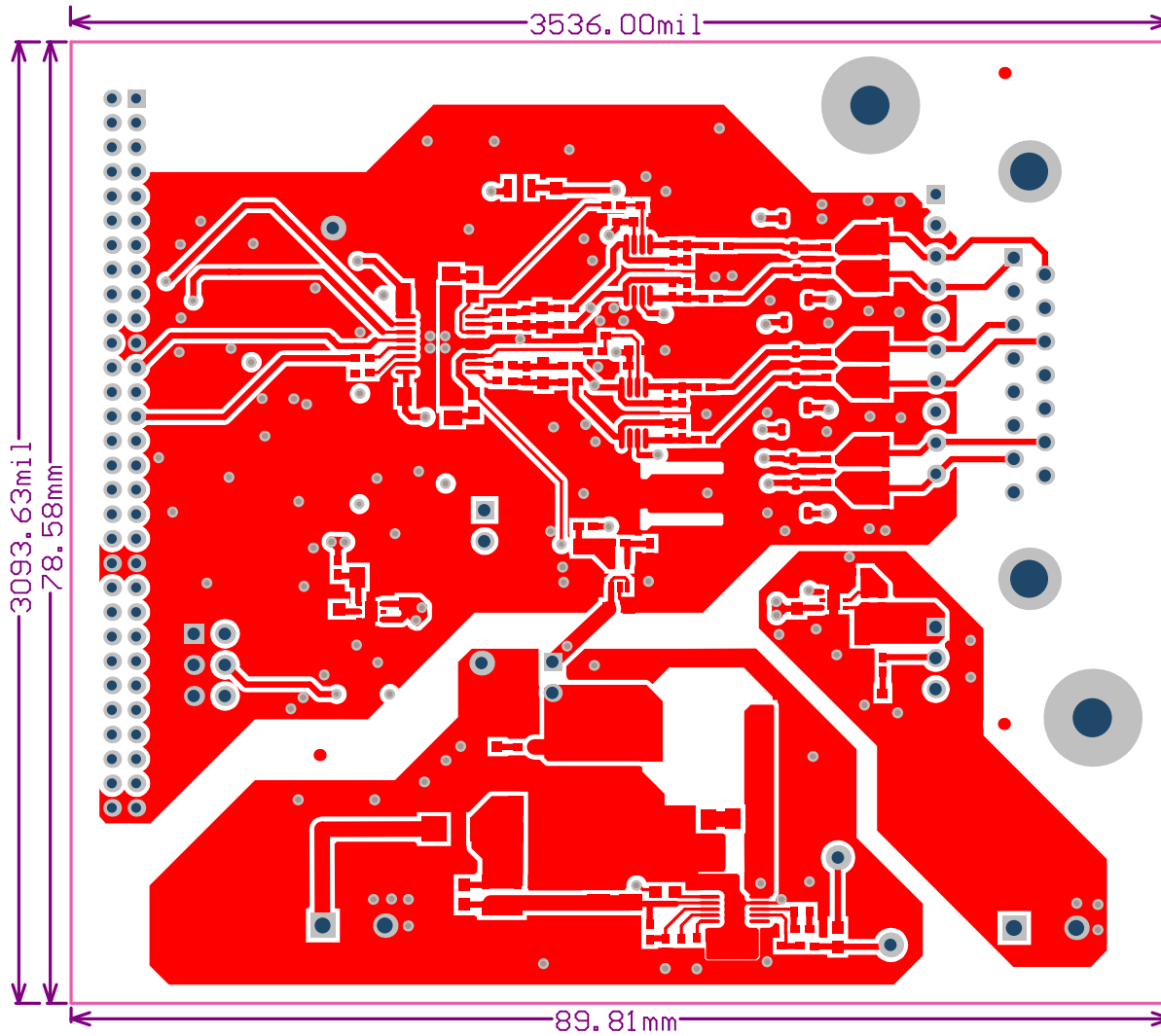
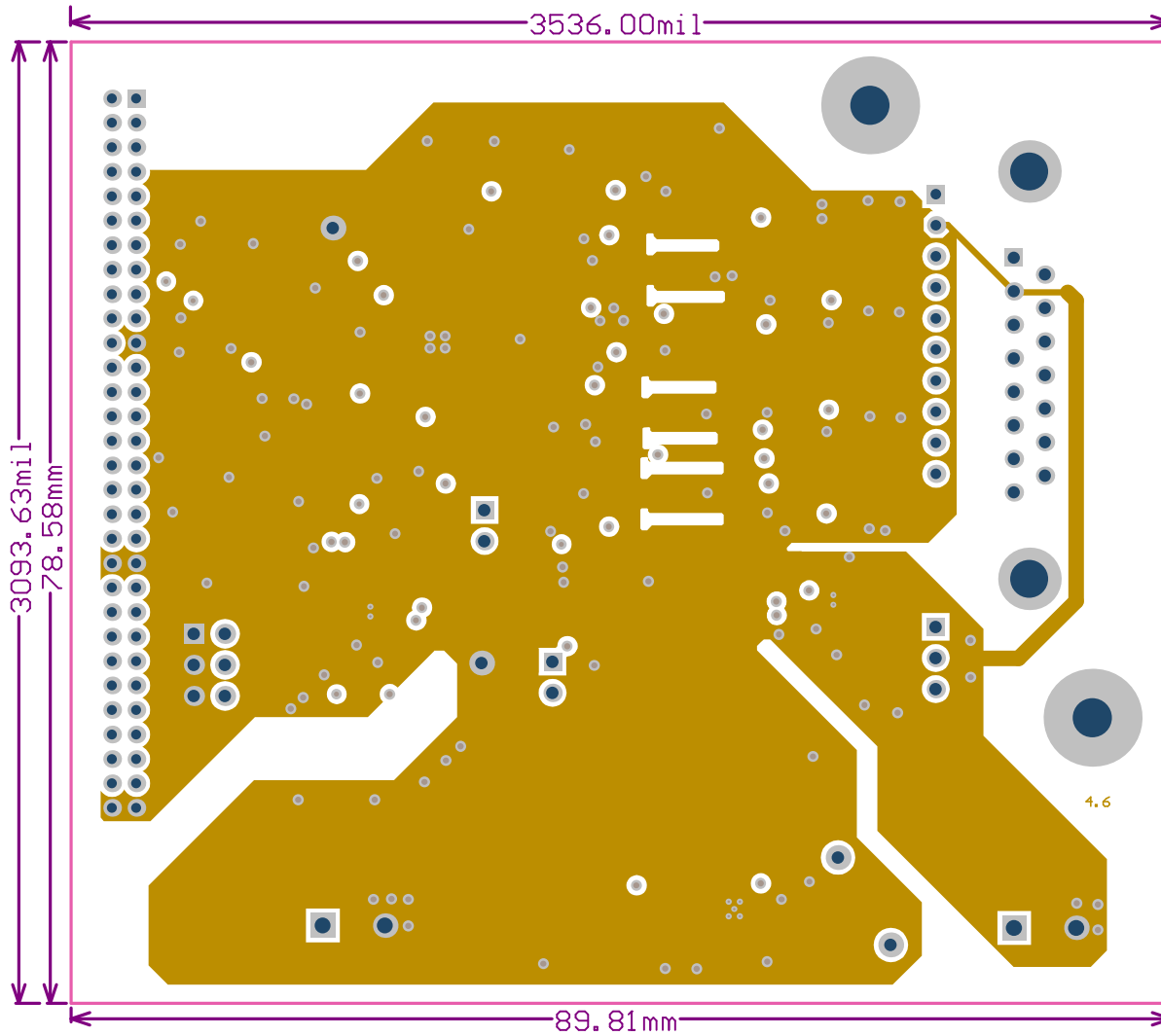


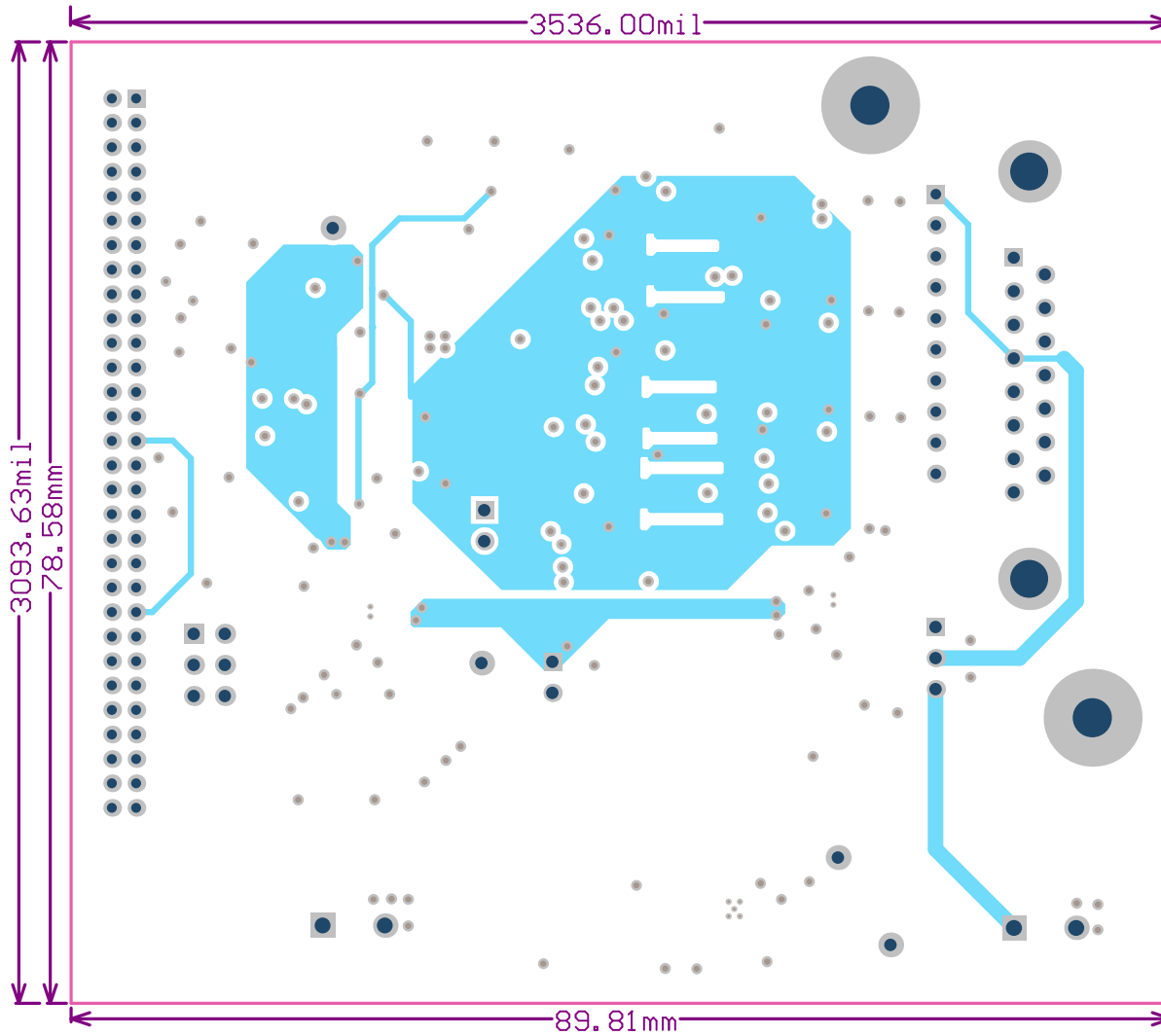
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00178	REV: Rev E1	SUN REV: Not In VersionControl
LAYER NAME = M@pB@r@d@e@Dimensions			
PLOT NAME = Top Solder Mask	GENERATED : 7/3/2015	2:47:43 PM	TEXAS INSTRUMENTS



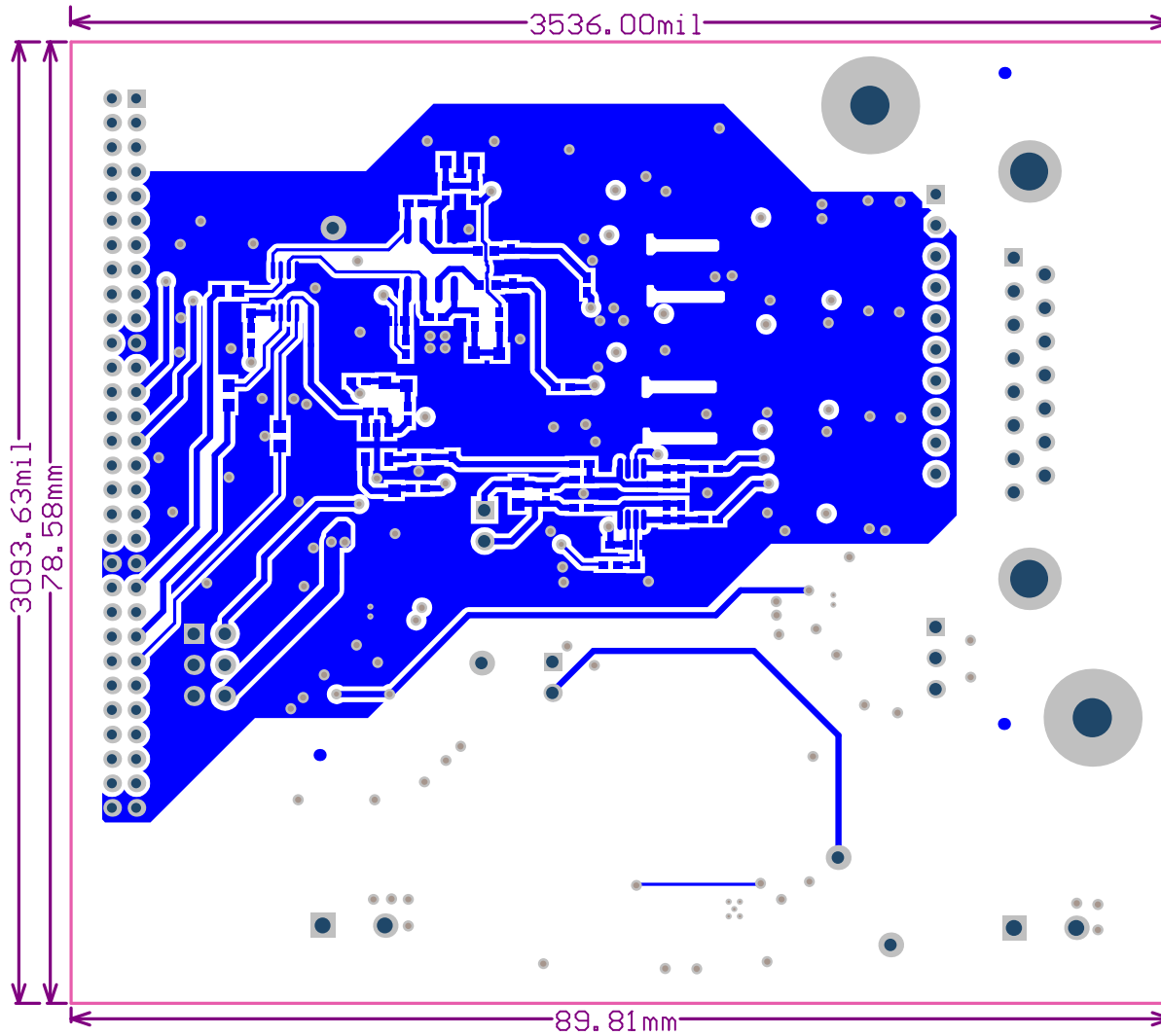
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00178	REV: Rev E1	SUN REV: Not In VersionControl
LAYER NAME = M@pBbagdrDimensions			
PLOT NAME = Top Layer	GENERATED : 7/3/2015	2:47:44 PM	TEXAS INSTRUMENTS



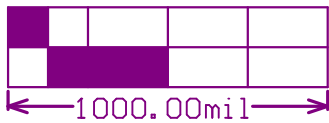
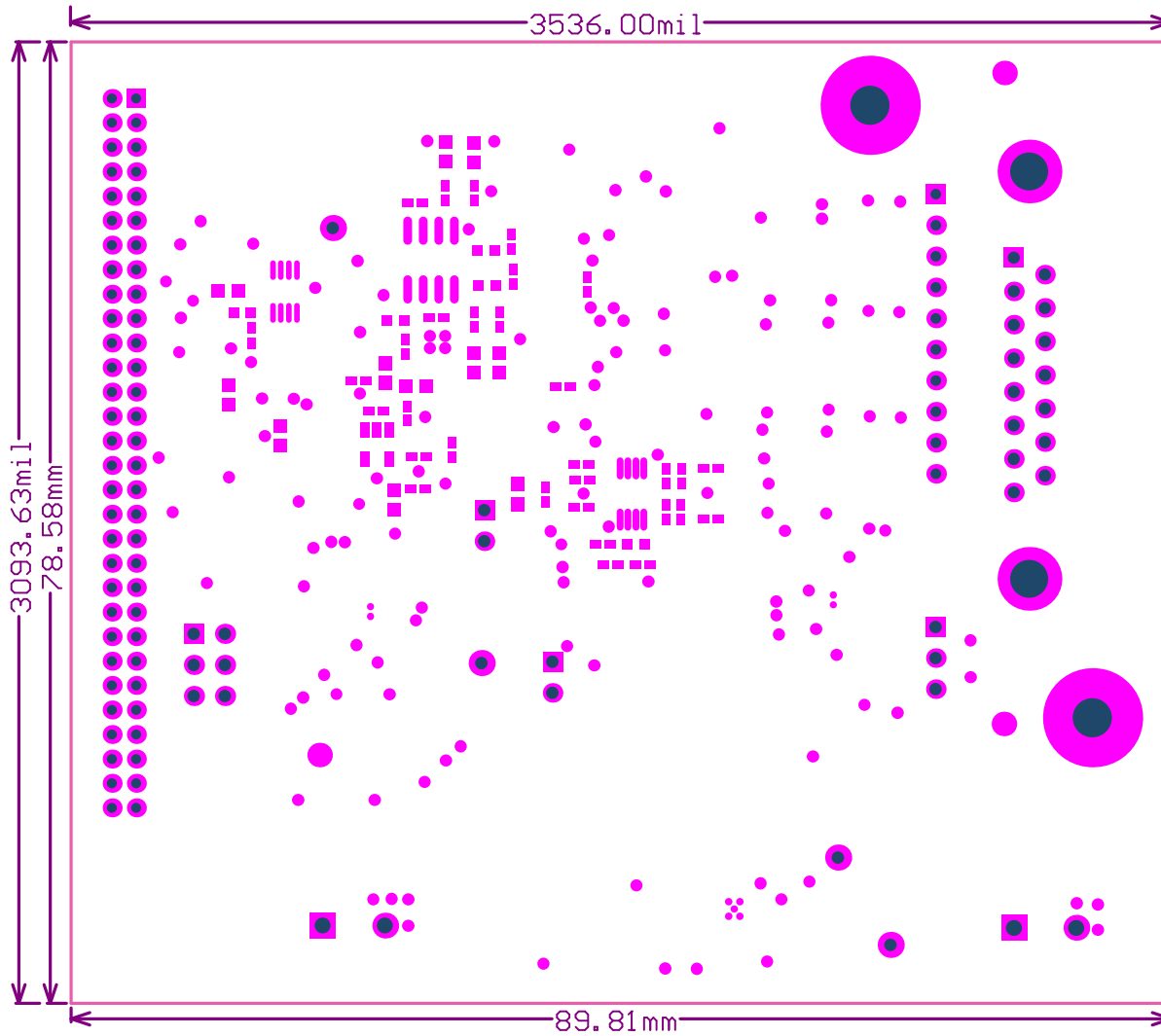
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00178	REV: Rev E1	SUN REV: Not In VersionControl
LAYER NAME = M20Board.plt Dimensions			
PLOT NAME = Mid Layer 1 - GND	GENERATED : 7/3/2015	2:47:45 PM	TEXAS INSTRUMENTS



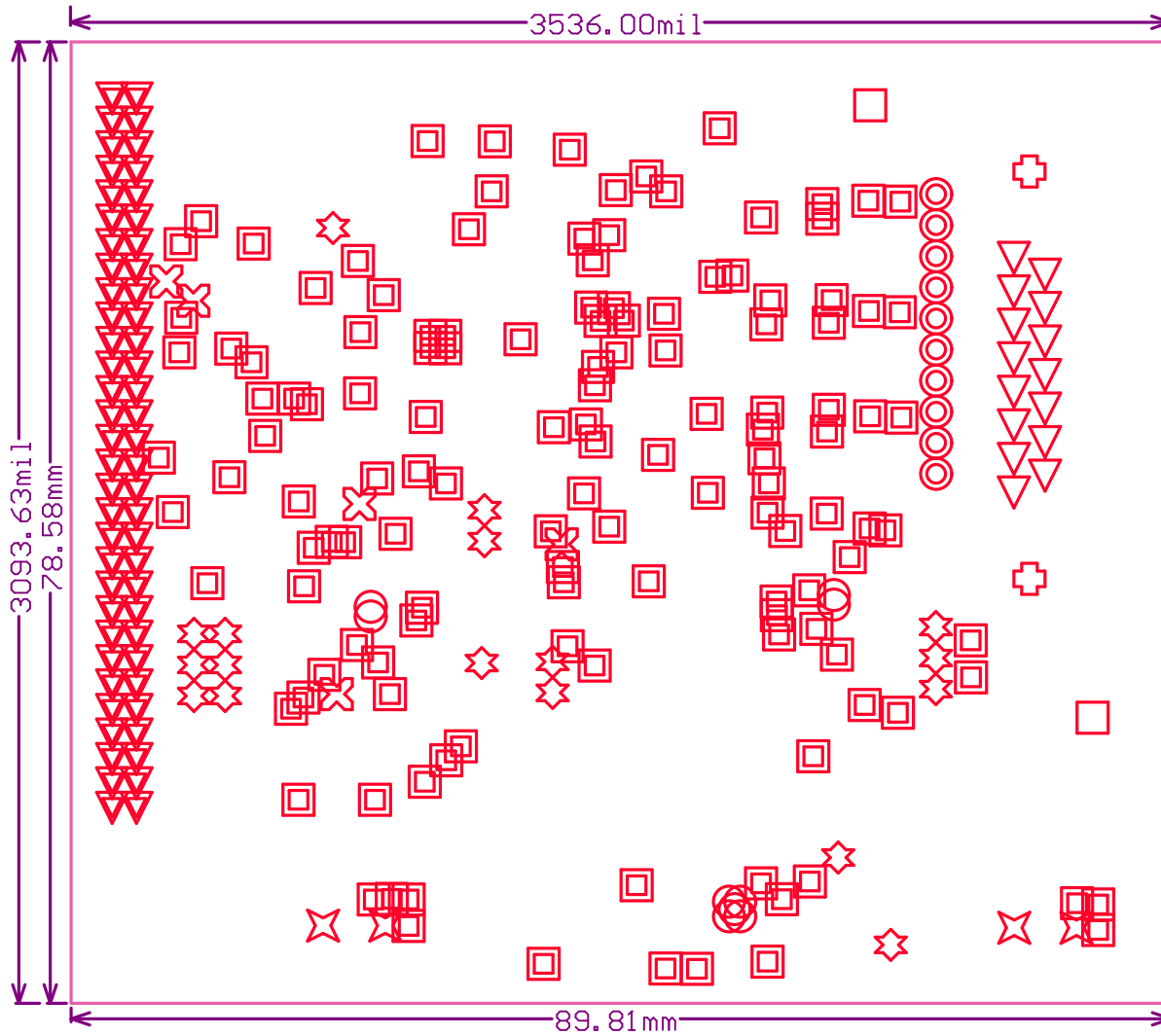
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00178	REV: Rev E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Mid Layer 2 - VCC	GENERATED : 7/3/2015	2:47:46 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00178	REV: Rev E1	SUN REV: Not In VersionControl
LAYER NAME = Bot Board Dimensions			
PLOT NAME = Bottom Layer	GENERATED : 7/3/2015	2:47:48 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00178	REV: Rev E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Bottom Solder Mask	GENERATED : 7/3/2015	2:47:50 PM	TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plate
○	9	7.87mil (0.200mm)	PTH
⊗	5	16.00mil (0.406mm)	PTH
■	136	19.69mil (0.500mm)	PTH
▼	60	32.00mil (0.813mm)	PTH
●	10	33.46mil (0.850mm)	PTH
▽	15	39.37mil (1.000mm)	PTH
☆	17	40.00mil (1.016mm)	PTH
⊗	4	51.18mil (1.300mm)	PTH
⊕	2	122.05mil (3.100mm)	PTH
□	2	125.98mil (3.200mm)	PTH
	260 Total		

ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: TIDA-00178

REV: Rev E1

SUN REV: Not In VersionControl

LAYER NAME = ~~12 Board Dimensions~~

PLOT NAME = Drill Drawing

GENERATED : 7/3/2015

2:47:53 PM

TEXAS INSTRUMENTS

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